



# Theoretical Aspects on Heat Transfer and Fluid Flow in Micro Channels

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**Abstract.** The past ten years have seen a lot of research on the issues of heat transfer and fluid flow in micro-channels. With an emphasis on upcoming research requirements, a critical analysis of the state of research as it stands is offered. Following a brief introduction, the study discusses six themes related to transport phenomena in micro-channels: condensation, cooling of electronics, single-phase gas flow, augmentation of single-phase liquid flow and flow boiling, and micro-scale heat exchangers. In this study, we investigate the three-dimensional heat transfer and water flow properties in a set of rectangular micro-channel heat sinks for advanced electronic systems. Over the past ten years, mini/micro channel type compact heat exchangers have received a lot of attention. The ability to make heat exchangers smaller, lighter, and cheaper than those in use now is the primary motivator. Additionally, emerging applications that call for the cooling of small things, such as electronics and micro-electro-mechanical devices, need for heat exchangers with tiny channels. Theoretically, it is examined how a nanofluid moves and transfers heat through a horizontal micro channel while being affected by a magnetic field and an electric double layer (EDL). The flow problem for a micro channel with a large aspect ratio is handled as a two-dimensional nonlinear system. The magnetic field and EDL body force are taken into account while calculating momentum equation.

**Keywords:** Heat Transfer, Micro Channels, Flow, Heat Sink

## 1. Introduction

With a view to save you its temperature from extensively growing and keep digital devices running at their best temperature, the increasing incorporation of electronic structures necessitates new, small-scale, and surprisingly effective cooling techniques. The heat produced in such a state of affairs has been controlled and eliminated using a diffusion of approaches. The use of micro-channel heat sinks is one such method. A liquid is pumped down those pathways to move the energy in a structure referred to as a micro-channel heat sink, which is positioned at the lower back of the microchip. It became indicating that the micro-channel warmth sinks are include micro-square waft passages, that have higher heat transfer coefficient in laminar glide regime than that during turbulent waft, via conventionally sized gadgets [1]. The fluid go with the flow traits and heat switch mechanism in micro channels are maximum essential programs within the thermal manage of digital devices [2, 3]. The recent facet of a thermoelectric cooler become cooled the use of micro channel warmth sinks with a trapezoidal go phase [4]. Micro fluidic structures, that have diverse uses in biomedical engineering, are also basically constructed at the waft of liquids and gases in micro-channels [5-7]. also, it become examined by using authors that, the pressured waft and warmth transmission houses of water and binary mixes flowing via rectangular micro channels had been thoroughly investigated. Additionally, while the micro channels length shrank, the important thing transition Reynolds variety decreased.

due to their great region-to-quantity ratio and fast rate of warmth transfer, micro channel warmth sinks have turn out to be a hot subject matter in power studies in current years and are therefore used in a spread of industries, which includes electronics, aerospace, refrigeration, chemical engineering, and bioengineering [8,9]. The waft and heat transfer in micro channels are strongly influenced by means of the sort and houses of the operating fluid in addition to the geometric parameters of the micro channels [10], and may hence fluctuate from what commonly occurs in macro channels that is supported by way of experimental records and widespread demonstration. In glass-capped silicon micro channels, the float of water and various organic fluids become studied. The measurements showed that the Darcy friction aspect changed into almost 50% better than expected via idea [11]. Its miles analyzed that, the flow of water and fluids in glass-crapped micro-channels [12]. in addition, studied water flowing through channels with square and trapezoidal pass sections. The micro channels right here shaped by using etching a silicon substrate and capping it with glass water. In trade manner, the small dimensions of microstructures [13] approximated the glide inside the micro channels as a porous fabric the usage of Darcy's law. Using the Brinkman-prolonged Darcy equation to provide analytical answers for velocity and temperature distributions for pressured convection in micro channel warmth sinks in the lawsuits of the 5th IASME/WSEAS international convention on warmth transfer, thermal engineering and surroundings, Athens, Greece, August 25-27, 2007 972 fluids go with the flow [14, 15].

The opposed roles performed by the slip velocity and the temperature jump that get up on the wall in gasoline segment convective warmth transfer in micro channels at the moment are very well understood and quantified. A full-size effort must be made in this regard, drastically for the measurement of temperature fields inside the fuel in micro channels, through the

usage of promising contemporary techniques as molecular tagging thermometry. On the other hand, only a few results assist the theoretical predictions (MTT). It's been proven that unmarried-section liquid float in micro channels behaves similarly to flows at large scales. The region of further enhancing performance is where there is presently a want. The adoption of waft boiling in micro channels is having hassle progressing because of the crucial warmness flux (CHF) restrictions and reduced warmness transfer coefficients relying on the scale at which the delivery residences are impacted, the concept of micro scale can vary. Most of the people of the micro scale attention are regularly on channel dimensions among 10 and 200 m, at the same time as a few packages, like single-phase liquid drift, boiling, and condensation, additionally show hobby in extra dimensions up to one to a few mm. Engineers and scientists are very interested in the observe of fluid glide and heat transfer in micro channels due to the fact there are many business packages for them, inclusive of micro channel heat sinks for cooling excessive energy, very massive-scale integration circuitry and laser diode arrays, warmness transfer enhancement in aerospace generation, micro-reactors for the evaluation of organic cells, and micro fluid pumps [16, 17]. Its miles observed that the behaviors of float and heat transmission at the micro scale fluctuate drastically from the ones on the macro scale. In evaluation to conditions in which items are of traditional size, transition and laminar warmness transfer arise in micro channels that are extraordinarily strange and complicated.

## 2. Methodology

Single-Phase Gas Flow in Micro channel: Convective heat transfer in fuel micro flows has been the challenge of numerous latest researches that have tested a selection of new packages related to the development of MEMS. In micro scale warmth exchangers, stress gauges, mass float and temperature sensors, micro pumps and Microsystems dedicated to blending or separation for nearby fuel evaluation, mass spectrometers, and Knudsen micro pumps, as an example, fuel micro flows with warmness switch occur. Long or short, possibly curved micro channels with one of kind go-sections are the essential additives of those Microsystems which are susceptible to warmness transmission. Because of rarefaction consequences, a neighborhood thermodynamic non-equilibrium is seen within the Knudsen layer near to the wall in those micro channels. With thermal antagonism results, it causes a velocity slip and a temperature jump at the wall. In contrast to the typical conduct in micro channels, the first occasion is more suitable even as the second, convective warmness switch is faded. A 3rd procedure that affects heat switch in micro channels is likewise vital to bear in mind: shear work delivered on via gasoline slide on the wall increases the quantity of viscous heating that contributes to convective heat switch.

Enhancement in Single-Phase Flow and Flow Boiling in Micro channels: Whilst passage dimensions are as small as 10 m, the fundamental liquid go with the flow conduct at the micro scale does not alternate. The equations created for macro scale programs, such as the Navier-Stokes equation and convective warmness shipping equations, are nevertheless usable because the liquid molecules are tightly packed collectively in contrast to the channel diameters. but, all through go with the flow boiling, the bubble sizes are pretty much like the size of the channel and are what cause modifications inside the two-segment float conduct and thermal houses. Recent research shows that warmness shipping in micro channels wishes to be advanced even extra. Consequently, an overview of the literature on this vicinity and the identity of precise research directions are the focus of this section [18].

Flow Boiling Instabilities in Micro channels:It's far well known that float boiling instabilities make it difficult to construct evaporative micro scale warmness exchangers. They are able to damage the gadgets structural integrity because they introduce temperature oscillations, thermal stress biking, vibration, and temperature oscillations. Extra appreciably, they'll trigger an early transition to the CHF circumstance this is restrictive. To cope with this issue, a number of unique studies groups have labored to higher understand the mechanisms governing glide instabilities at the micro scale and to create strategies for suppressing their harmful outcomes [19,20]. This study has improved our qualitative information of the character of waft instabilities in micro scale environments. Quantitative methods and fashions to extra correctly forecast the prevalence and severity of those go with the flow instabilities, however, are still a long way from good enough. Moreover, extra effective strategies ought to be created to address the difficulties brought on by way of drift instabilities [21]. Electronics are getting smaller nowadays. These devices generate numerous warmth due to their tiny design. Therefore, warmness should be continuously removed from this device for protection reasons. Consequently, the purpose of the cooling machine is to preserve the temperature inside a selected variety, such as,

- Natural Cooled warmness Sink
- Forced Cooled warmness Sink
- Superconducting Radiators

All of these conventional cooling strategies are effective whilst the warmth dissipation price is less than a hundred  $W/cm^2$ ; however they come to be useless at cooling the gadgets whilst the fee exceeds  $100 W/cm^2$ . Applied are micro channel heat sinks. Inside the years for the reason that their initial introduction in 1981, micro channel warmness sinks have been the challenge of tremendous research. a specially designed to enhance the performance of the micro channel warmness sink. The essential benefit of the micro channel warmness sink is its excessive warmth switch coefficient and occasional thermal resistance. For electrical equipment with confined area, micro channel warmness sinks are recognized as one of the most effective heat removal methods.

**Physical Model and Computational Domain:** Heat is mainly extracted from the strong through conduction, and its miles sooner or later expelled through convection of the cooling fluid in the micro channel. The silicon micro channel beneath study has a thermal conductivity (K) of 148 W/mK. A chip of electricity linked to the micro channel at the lowest emits a consistent warmth flux of  $q$  into the surrounding space. There may be a Pyrex plate that creates an adiabatic country on the top of the channels.  $W_c$  and  $W_s$ , respectively, stand for the wall thickness and the width of micro channels. According to Fig. 1, the silicon substrate's thickness,  $H_t - H_c$ , may be used to identify how the heat flux is transformed to cooling fluid flowing via channels.

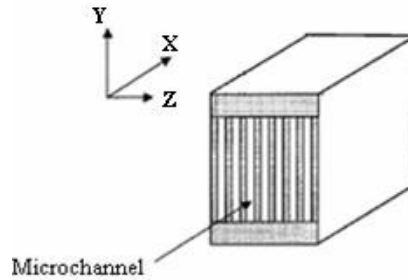


FIGURE 1. Schematic Diagram of Micro channel [22]

Moreover, continuous radioactive warmth transfer, negligible incompressible and laminar fluid motion, and steady strong and fluid residences have all been assumed in calculations. Cooling water getting into the channels has an input temperature of  $20^{\circ}\text{C}$ . Within the ongoing studies, a micro channel inside the plate's centre can be taken under consideration. We will listen the computational domain in a half of channel as indicated in Fig. 1 because of the symmetry of the rectangular channel fig. three.

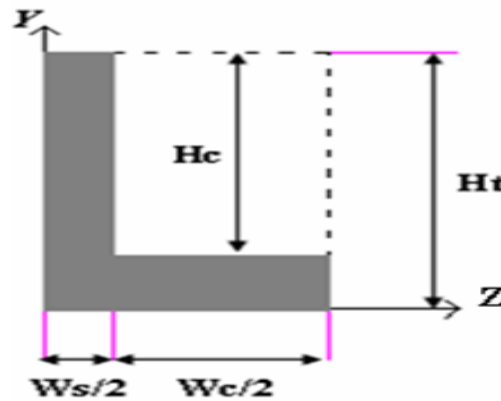


FIGURE 2. Physical Model [22]

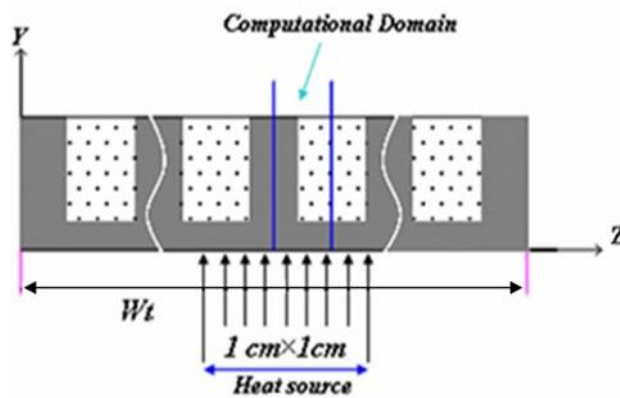


FIGURE 3. Computational Domain [22]

### 3. Condensation in Micro channels

**Recent Advances:** Many fundamental principles are shared with the aid of condensation, evaporation, and boiling, but the motivations for research in those regions have various. Condensation is generally related to warmth rejection and is commonly paired with higher thermal resistances from unmarried-section coupling fluids or ambient air. at the same time as boiling and evaporation have been important for the development of high-heat flux heat removal from compact devices in

packages like electronics cooling, condensation is normally associated with warmth rejection. Acquiring an essential understanding of condensation at the micro scale acquires growing relevance with the developing awareness on device-level metrics together with universal electricity performance, decreases in heat transfer gadget size, and the use of ecologically acceptable working fluids.

Many essential ideas are shared by condensation, evaporation, and boiling, however the motivations for research in those regions have various. Condensation is normally connected to warmth rejection and is typically paired with higher thermal resistances from unmarried-segment coupling fluids or ambient air. While boiling and evaporation have been vital for the advancement of high-heat flux heat elimination from compact devices in applications like electronics cooling, condensation is generally associated with warmth rejection. Acquiring a fundamental expertise of condensation at the micro scale acquires increasing relevance with the developing consciousness on gadget-level metrics which include usual strength performance, decreases in warmth switch equipment size, and using ecologically suitable working fluids.

The relative relevance of floor anxiety when it comes to gravity increases because the drift route length decreases. As an end result, its miles not going that condensation models created for bigger tubes, where gravity and inertial forces predominate, will accurately assume the behavior at small dimensions. Therefore, there's a pressing want for dependable condensation heat transfer and stress drop models that can be carried out to an extensive range of working fluids, micro scale geometries, and operating situations. Even within the maximum fundamental size of heat switch charges, condensation procedures present limitations distinctive from those encountered in boiling and evaporation. The past ten years have visible improvements in experimental and modeling techniques lay the inspiration for an intensive knowledge of condensation at the micro scale.

#### 4. Research Needs- Condensation in Micro channels

Cutting-edge research focuses on micro channel condensation as an awesome entity with wonderful regulating factors. Innovative high-speed visualization strategies have furnished complete qualitative and quantitative facts approximately the principal flow regimes, the standards for switching between them, and the distribution of the liquid-vapor section wanted for void fraction models. Models that explicitly take into consideration micro scale phenomena had been produced using waft mechanism records together with shear and momentum balance assessments in diverse areas of intermittent and annular float. Heat switch coefficients produced with the aid of dimension strategies created to address issues unique to high flux heat transfer at low heat hundreds have a tendency to be regular throughout numerous research agencies. Surface tension, gravitational, viscous, and inertial forces have all been efficaciously highlighted by way of computational techniques. These strategies have additionally furnished proof for the higher  $h$  in surface tension-dominated flows in channels with sharp corners.

The constraints of optical float visualization encompass the problem of identifying interfaces as  $D/h$  decreases. For this place to boost, methods that could produce facts at such small scales—possibly thru nonintrusive capacitance/impedance measurements—without the need to optically music difficult interfaces are required. However, as they are carried out to numerous fluids, geometries, and running situations, flow regime maps and transition standards lose a number of their predictive power. The introduction of a waft regime map which can do not forget many fluid types, such as manufactured refrigerants and their isotropic blends, natural fluids like ammonia, steam, CO<sub>2</sub>, water, and hydrocarbons for the duration of a wide range of  $P$ ,  $R$  and  $D/h$ , is consequently vital. More sensible idealizations of the governing elements that because the waft to gravitate in the direction of one regime or the alternative throughout the many transition borders those researchers had been capable of visualize can be important for this. By using the use of such transition criteria, multiregime models for segment distributions will be produced that are correspondingly better and they want to pick out void fraction correlations at random in an effort to provide closure to  $h$  and  $D/p$  fashions. Then, instead of focusing normally on annular drift, heat transfer fashions can develop to those who directly account for delivery in intermittent and other flows in addition to the varying impacts of tube form, floor tension, and fluid assets differences over a lot wider ranges than is currently possible.

#### 5. Applications of Micro channels in Electronics Cooling

**Brief Timeline of Advances:** The most obtrusive supply of heat that triggered unreliability in each the vacuum tubes themselves and adjoining components turned into their comically heated cathodes. The commonplace goals have been capacitors. The problem turned into significantly resolved when semiconductor gadgets took the area of vacuum tubes. The advent of computers, however, ended in a huge rise within the density and standard populace of warmth dissipation devices, rendering simple spreading useless. As an end result, several types of liquid cooling were developed [23]. Extraordinary kinds of 3-D included circuits are presently being evolved. Finished chips are positioned on pinnacle of one another and joined at the rims in their most simple and famous shape. The arrangement of intertie connections the use of a variety of via silicon vias is the subsequent level this is being studied in a kingdom of speedy development. Those strategies could be categorized as state-of-the-art packaging [24].

#### 6. Research Needs in Application of Micro channels Electronics Cooling

Future generations of electronics cannot be developed without advancements in thermal control. These improvements can be made by taking use of the chances provided by new materials and structures, considerably enhanced modeling methods that depend on cutting-edge computing devices and a resurgence of new algorithms and similar methods coming from computer science departments. Although it is difficult to forecast when new configurations will be created, funding organizations should be prepared to examine and support pilot projects that test out novel concepts with the logical potential to address some of the aforementioned difficulties. Future cooling solutions will necessitate greater cooperation between the electronics thermal engineers, material scientists, reliability experts, circuit designers, and micro fabrication engineers. However, the final success of novel methods that significantly increase cooling capacities rests on our capacity to produce working devices in a manner that is cost-competitive.

## 7. Applications of Micro channels in Heat Exchangers

The proportions of the geometrical components of heat switch devices are altered with the aid of miniaturization. The use of the scaling factor  $S$ , the effect of the alternate in dimensions can be measured. The validity of conventional warmth transfer correlations as implemented to the prediction of heat switch conduct in micro channel warmth exchangers has been the situation of several theoretical and experimental research that have been published within the final ten years [25]. International, micro scale warmth exchangers were developed, produced, and examined in an expansion of applications. There are currently numerous business suppliers of micro scale warmth exchangers made from metallic, ceramic, glass, and/or plastic, that is a main development over in advance attempt. Formerly, the simplest alternative became to purchase very specialized prototype gadgets for lab investigations. As a result, micro scale warmth exchangers have partly left the laboratory and end up commercially available goods. The desires of the applications that have been mentioned to this point are as an alternative varied. In electronics cooling, the objective is frequently to keep a totally low fluid strain drop even as minimizing thermal resistance in a small extent. The warmth exchangers utilized in offshore packages and system engineering, in assessment, are frequently created to supply extraordinarily high-electricity density at excessive stress degrees and excessive temperatures while minimizing vulnerability to corrosion and fouling. Right here, efficiency profits and extent savings at the vicinity of an offshore platform or chemical plant are the main drivers of the improvement; strain losses are huge but no longer the principle driving force [26-29].

## 8. Properties of Working Fluid

- **Water:** Warm water vibrates than the cold water. The thermal conductivity of water is high and rises it up to maximum at about 130-degree C. Water has high viscosity.
- **Ethanol:** It is a colorless liquid with pleasant smell. It is completely miscible with water and organic solvents and it is very hygroscopic.
- **Methanol:** It appears as a colorless fairly volatile liquid with faintly sweet pungent odor like that of ethyl alcohol. It comparatively mixes with water. The vapors are slightly heavier than air.
- **Ammonia:** It is colorless gas with a characteristically pungent smell. It is lighter than the air, its density being 0.589 times that of air.

## 9. Conclusion

This looks at has tested the warmth shipping in 4 specific geometries of micro channel warmth sinks. single-segment gas flow, unmarried-segment liquid goes with the flow, go with the flow boiling, and glide condensation are essential worries related to transport tactics that have been thoroughly researched, and the published literature offers a strong information of those phenomena. The concurrent research of nanoscale traits and transport approaches is opening up new possibilities. New opportunities for improving the effectiveness and applicability of the micro channel delivery tactics are rising due to trends in micro fluidics, MEMS generation, and the synthesis and characterization of nonmaterials. The take a look at module is packed with various operating fluids and the heat transfer ability is decided via the operating temperature. Additionally, they checked out how nicely these numerous working fluids transferred warmth other than water, we also noticed that the heat switch potential of the other four running fluids elevated because the working temperature rose. And within the case of water, the ability for heat transmission will increase quickly because the operating temperature rises. Consequently, we may also finish that amongst all working fluids; water can produce the quality consequences. The running temperature fluctuates with the heat switch capacity, as seen inside the following graph.

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